

0.8% LOW VOLTAGE DETECTOR

NO.EA-160-160226

OUTLINE

The R3114x series are CMOS-based voltage detector ICs with high detector threshold accuracy and ultra-low supply current, which can be operated at an extremely low voltage and is used for system reset as an example.

Each of these ICs consists of a voltage reference unit, a comparator, resistors for detector threshold setting, an output driver and a hysteresis circuit. The detector threshold is fixed with high accuracy internally and does not require any adjustment.

Two output types, Nch open drain type and CMOS type are available.

The R3114x series are operable at a lower voltage than that of the R3111x series, and can be driven by a single battery.

Three types of packages, SOT-23-5, SC-82AB, and DFN(PL)1010-4 are available.

FEATURES

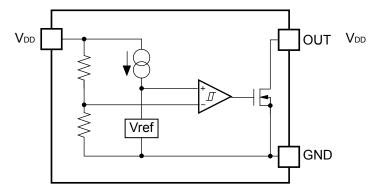
- Operating Voltage Range......0.5V to 6.0V (Topt=25°C)
- Detector Threshold Range......0.7V to 5.0V (0.1V steps)
 - (For other voltages, please refer to MARK INFORMATIONS.)
- Temperature-Drift Coefficient of Detector Threshold Typ. ±30ppm/°C
- Output Types.....Nch Open Drain "L" and CMOS
- Packages DFN(PL)1010-4, SC-82AB, SOT-23-5

APPLICATIONS

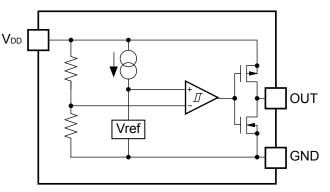
- CPU and Logic Circuit Reset
- Battery Checker
- Window Comparator
- Wave Shaping Circuit
- Battery Back-up Circuit
- Power Failure Detector

BLOCK DIAGRAMS

Nch Open Drain Output (R3114xxx1A)



CMOS Output (R3114xxx1C)



SELECTION GUIDE

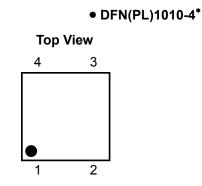
The package type, the detector threshold, the output type and the taping type for the ICs can be selected at the users' request.

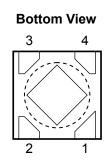
Product Name	Package	Quantity per Reel	Pb Free	Halogen Free					
R3114Kxx1*-TR	DFN(PL)1010-4	10,000 pcs	Yes	Yes					
R3114Qxx1*-TR-FE	SC-82AB	3,000 pcs	Yes	Yes					
R3114Nxx1*-TR-FE	SOT-23-5	3,000 pcs	Yes	Yes					
xx: The detector thresh (For other voltages,	xx: The detector threshold can be designated in the range from 0.7V(07) to 5.0V(50) in 0.1V steps. (For other voltages, please refer to MARK INFORMATIONS.)								

Designation of Output Type

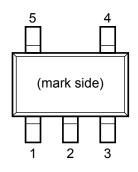
 (A) Nch Open Drain
 (C) CMOS

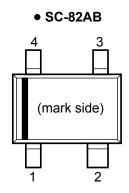
PIN CONFIGURATIONS











PIN DESCRIPTIONS

• DFN(PL)1010-4*

Pin No.	Symbol	Description
1	OUT	Output Pin ("L" at detection)
2	NC	No Connection
3	GND	Ground Pin
4	Vdd	Input Pin

 *) Tab is GND level. (They are connected to the reverse side of this IC.) The tab is better to be connected to the GND, but leaving it open is also acceptable. • SOT-23-5

1	Pin No.	Symbol	Description
	1	OUT	Output Pin ("L" at detection)
	2	Vdd	Input Pin
	3	GND	Ground Pin
	4	NC	No Connection
	5	NC	No Connection

• SC-82AB

Pin No.	Symbol	Description
1	OUT	Output Pin ("L" at detection)
2	Vdd	Input Pin
3	NC	No Connection
4	GND	Ground Pin

ABSOLUTE MAXIMUM RATINGS

Symbol	Item	Rating	Unit
Vdd	Supply Voltage	7.0	V
Vout	Output Voltage (Nch Open Drain Output)	Vss-0.3 to 7.0	V
VOUT	Output Voltage (CMOS Output)	Vss-0.3 to Vdd+0.3	v
Іоит	Output Current	20	mA
	Power Dissipation (SOT-23-5)*	420	
PD	Power Dissipation (SC-82AB)*	380	mW
	Power Dissipation (DFN(PL)1010-4)*	400	
Topt	Operating Temperature Range	-40 to 85	٥C
Tstg	Storage Temperature Range	-55 to 125	٥C

*) For Power Dissipation, please refer to PACKAGE INFORMATION.

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field.

The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS (ELECTRICAL CHARACTERISTICS)

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

ELECTRICAL CHARACTERISTICS

• R3114xxx1A/C values indicate $-40^{\circ}C \le T_{opt} \le 85^{\circ}C$, unless otherwise noted. Topt=25°C

Symbol	Item		Cond	litions		Min.	Тур.	Max.	Unit
		Topt=25	5°C	1.5V <	$-V_{\text{DET}} \leq 5.0V$	-V _{DET} × 0.992		-V _{DET} ×1.008	V
N	Detector Threshold			$0.7V \leq \text{-}V_{\text{DET}} \leq 1.5V$		-12		+12	mV
-Vdet	Detector Threshold		≤ Topt ≤	1.5V <	$V_{\text{DET}} \leq 5.0V$	-V _{DET} × 0.985		-V _{DET} × 1.015	V
		85°C		0.7V ≤ -	$V_{\text{DET}} \le 1.5V$	-22.5		+22.5	mV
V _{HYS}	Detector Threshold Hysteresis							$-V_{DET} \times 0.07$	V
				0.7V ≤ -	Vdet < 1.6V			1.40	
			0 1)/	1.6V ≤ -	Vdet < 3.1V			1.50	
		VDD=-VDET -0.1V 3.1		3.1V ≤ -	VDET < 4.1V			1.60	
lss	$ \begin{tabular}{ c c c c c } \hline \mbox{Detector Threshold} & $$T_{opt=25^{\circ}C}$ & $$1.5V < -V_{DET} \leq 5.0V$ & $$$.0V_{0} < $$$$$$.00V_{0} < $$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$$	1.70	۸						
155	Supply Current			0.7V ≤ -	Vdet < 1.6V			1.20	μA
		VDD=-VDET +1.0V		1.6V ≤ -	$1.6V \leq -V_{\text{DET}} < 3.1V$			1.20	
				$3.1V \leq -V_{\text{DET}} < 4.1V$				1.30	
			$4.1V \leq -V_{\text{DET}} \leq 5.0V$					1.40	L
Vddh	Maximum Operating Voltage						6	V	
Vddl	Minimum Operating	Topt=25	5°C					0.50	V
VDDL	Voltage ^{*1}	-40°C	\leq Topt \leq 85°C					0.55	v
			VDD=0.55V, VDS=0.05V			7			μA
			$0.7V \leq -V_{\text{DET}}$	$(V) < V_{DET} < 1.1V$		0.02			- mA
		Nch	$1.1V \leq -V_{\text{DET}}$	$1 V < V_{DET} < 1 6 V$		0.40			
Ιουτ	•		$1.6V \leq -V_{DET} < 3.1V$			1.00			
			$3.1V \leq -V_{\text{DET}}$	≤ 5.0V		2.40			
		Dah*2	$0.7V \leq -V_{\text{DET}}$	$0.7V \le -V_{DET} < 4.0V$		0.65			m (
		PCn ²	$4 (1) \sqrt{3} < -\sqrt{2} \sqrt{2} \sqrt{3} \sqrt{3}$			0.90			mA
ILEAK	Nch Driver Leakage Current*3	VDD=6.0	0V, Vds=7.0V					80	nA
Δ -V _{DET} / Δ Topt	Detector Threshold Temperature Coefficient						±30		ppm /°C
t _{PLH}	Output Delay Time	VDD=0.	55V to -VDET+2	2.0V or 6.0)V		40		μS

All of unit are tested and specified under load conditions such that Topt=25°C except for Detector Threshold Temperature Coefficient.

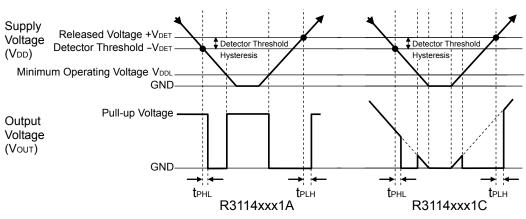
*1: Minimum operating voltage means the value of input voltage when output voltage maintains 0.1V or less.

(In case of Nch Open Drain Output type, the output pin is pulled up with a resistance of $470k\Omega$ to 5.0V)

*2: In case of CMOS type

*3: In case of Nch Open Drain type

TIMING CHART



DEFINITION OF OUTPUT DELAY TIME

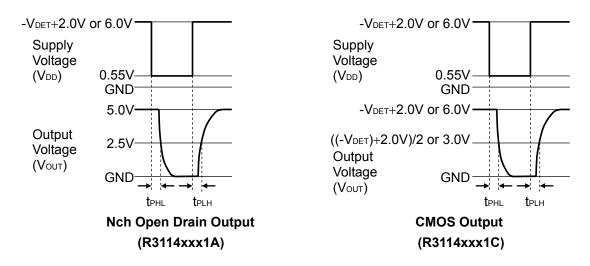
Output Delay Time (tPLH) is defined as follows:

1. In the case of Nch Open Drain Output:

Under the condition of the output pin (OUT) is pulled up through a resistor of $470k\Omega$ to 5V, the time interval between the rising edge of V_{DD} pulse from 0.55V to (-V_{DET})+2.0V or the time interval of 6.0V pulse voltage is supplied, the becoming of the output voltage to 2.5V.

2. In the case of CMOS Output:

The time interval between the rising edge of V_{DD} pulse from 0.55V to $(-V_{DET})+2.0V$ or the time interval of 6.0V pulse voltage is supplied, the becoming of the output voltage to $((-V_{DET})+2.0V)/2$ or 3.0V.



ELECTRICAL CHARACTERISTICS BY DETECTOR THRESHOLD

• R3114x071A/C to R3114x501A/C

Bold values are checked and guaranteed by design engineering at $-40^{\circ}C \le Topt \le 85^{\circ}C$, unless otherwise noted.

				-		_						Topt=25°C
Part		ector hold1		ector hold2	Detector Threshold Hysteresis		Supply Current1		Supply Current2		Max. Op. Voltage	Min. Op. Voltage
Number	-VDE	т1 [V]	-Vde	T2 [V]	Vнү	rs [V]	Iss1	[µA]	Iss2	lss2 [µA]		VDDL [V]
	Min.	Max.	Min.	Max.	Min.	Max.	Cond.	Max.	Cond.	Max.	Max.	Max.
R3114x071A/C	0.6880	0.7120	0.6775	0.7225	0.028	0.049						
R3114x081A/C	0.7880	0.8120	0.7775	0.8225	0.032	0.056						
R3114x091A/C	0.8880	0.9120	0.8775	0.9225	0.036	0.063						
R3114x101A/C	0.9880	1.0120	0.9775	1.0225	0.040	0.070						
R3114x111A/C	1.0880	1.1120	1.0775	1.1225	0.044	0.077		1.400				
R3114x121A/C	1.1880	1.2120	1.1775	1.2225	0.048	0.084						
R3114x131A/C	1.2880	1.3120	1.2775	1.3225	0.052	0.091						
R3114x141A/C	1.3880	1.4120	1.3775	1.4225	0.056	0.098						
R3114x151A/C	1.4880	1.5120	1.4775	1.5225	0.060	0.105						
R3114x161A/C	1.5872	1.6128	1.5760	1.6240	0.064	0.112						
R3114x171A/C	1.6864	1.7136	1.6745	1.7255	0.068	0.119						
R3114x181A/C	1.7856	1.8144	1.7730	1.8270	0.072	0.126				1.200		
R3114x191A/C	1.8848	1.9152	1.8715	1.9285	0.076	0.133						
R3114x201A/C	1.9840	2.0160	1.9700	2.0300	0.080	0.140						
R3114x211A/C	2.0832	2.1168	2.0685	2.1315	0.084	0.147						
R3114x221A/C	2.1824	2.2176	2.1670	2.2330	0.088	0.154		4 500			6	
R3114x231A/C	2.2816	2.3184	2.2655	2.3345	0.092	0.161		1.500				
R3114x241A/C	2.3808	2.4192	2.3640	2.4360	0.096	0.168						
R3114x251A/C	2.4800	2.5200	2.4625	2.5375	0.100	0.175						0.50
R3114x261A/C	2.5792	2.6208	2.5610	2.6390	0.104	0.182						
R3114x271A/C	2.6784	2.7216	2.6595	2.7405	0.108	0.189	VDD=		VDD=			
R3114x281A/C R3114x291A/C	2.7776 2.8768	2.8224 2.9232	2.7580 2.8565	2.8420 2.9435	0.112	0.196	-Vdet		-Vdet			0.55
R3114x291A/C	2.9760	3.0240	2.8565	3.0450	0.110	0.203	-0.1V		+1.0V			
R3114x301A/C									_			
R3114x321A/C	3.0752 3.1744	3.1248 3.2256	3.0535 3.1520	3.1465 3.2480	0.124	0.217 0.224						*Note1
R3114x321A/C	3.1744	3.3264	3.2505	3.3495	0.120	0.224						
R3114x331A/C	3.3728	3.4272	3.3490	3.4510	0.132	0.231						
R3114x351A/C	3.4720	3.5280	3.4475	3.5525	0.130	0.235						
R3114x361A/C	3.5712	3.6288	3.5460	3.6540	0.140	0.245		1.600		1.300		
R3114x371A/C	3.6704	3.7296	3.6445	3.7555	0.144	0.259						
R3114x381A/C	3.7696	3.8304	3.7430	3.8570	0.152	0.266						
R3114x391A/C	3.8688	3.9312	3.8415	3.9585	0.152	0.273						
R3114x401A/C	3.9680	4.0320	3.9400	4.0600	0.160	0.280						
R3114x401A/C	4.0672	4.1328	4.0385	4.1615	0.164	0.287					1	
R3114x421A/C	4.1664	4.1326	4.0385	4.1613	0.164	0.294						
R3114x431A/C	4.2656	4.3344	4.1370	4.3645	0.172	0.294						
R3114x441A/C	4.3648	4.4352	4.3340	4.4660	0.172	0.308						
R3114x451A/C	4.4640	4.5360	4.4325	4.5675	0.180	0.305						
R3114x461A/C	4.5632	4.6368	4.5310	4.6690	0.184	0.313		1.700		1.400		
R3114x471A/C	4.6624	4.7376	4.6295	4.7705	0.188	0.329						
R3114x481A/C	4.7616	4.8384	4.7280	4.8720	0.192	0.336						
R3114x491A/C	4.8608	4.9392	4.8265	4.9735	0.196	0.343						
	4.9600	5.0400	4.9250	5.0750	0.200	0.350		1		1	1	1

*Note1) VDD value when output voltage is equal or less than 0.1V. In the case of Nch Open Drain output type, the output pin is pulled up to 5.0V through 470kΩ resistor.

R3114x

Curr	Nch Driver Output Current1 IouT1 [µA]		Nch Driver Output Current2 Ioutz [mA]		Pch Driver Output Current Ioutt3 [mA]		Driver Current	Detector Threshold Temperature Coefficient	Output Tim	ne
							([nA]	∆-VDET/∆Topt [ppm/°C]	tPLH	
Cond.	Min.	Cond. V _{DD} = 0.6V V _{DS} = 0.5V	Min. 0.020	Cond.	Min.	Cond.	Max.	Тур.	Cond.	Тур.
		V _{DD} = 1.0V V _{DS} = 0.5V	<mark>0.400</mark>							
VDD= 0.55V VDS=	7	VDD= 1.5V VDS= 0.5V	<mark>1.000</mark>	VDD= 4.5V VDS= -2.1V	<mark>0.650</mark>	V _{DD} = 6.0V V _{DS} = 7.0V	80	±30	V _{DD} = 0.55V ↓ -VDET +2.0V *Note2	40
0.05V		VDD= 3.0V VDS= 0.5V	2.400	VDD= 6.0V VDS=	0.900				VDD= 0.55V ↓ 6.0V	
				VDS= -2.1V	0.900				6.0V ∗Note2	

*Note2) 1. In the case of CMOS output type:

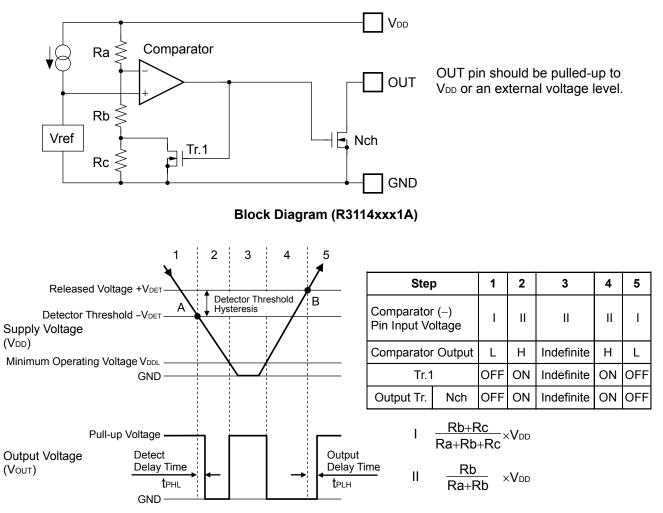
When the voltage is forced from 0.55V to $(-V_{DET})+2.0V$ or a 6.0V pulse voltage is added to V_{DD} , time interval that the output voltage reaches $((-V_{DET})+2.0V)/2$ or a 3.0V.

2. In the case of Nch Open Drain output type:

The output pin is pulled up to 5.0V through $470k\Omega$, and when the voltage is forced from 0.55V to (-V_{DET})+2.0V or a 6.0V pulse voltage is added to V_{DD}, time interval that the output voltage reaches 2.5V.

OPERATION

• Operation of R3114xxx1A



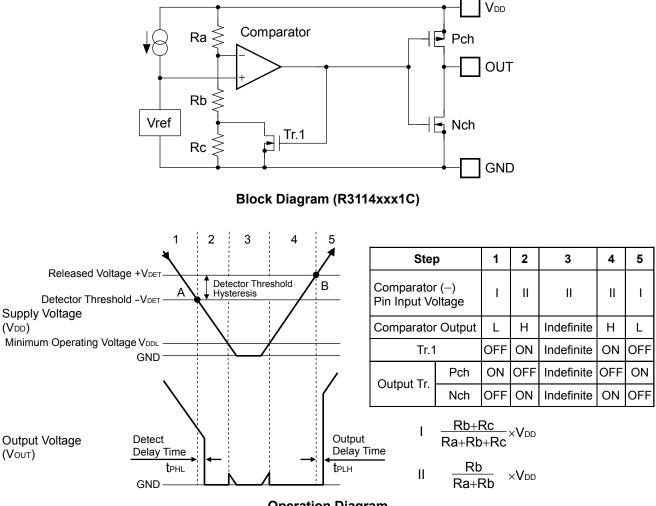


• Explanation of operation

Step 1. The output voltage is equal to the pull-up voltage.

- Step 2. At Point "A", Vref ≥ V_{DD}×(Rb+Rc)/(Ra+Rb+Rc) is true, as a result, the output of comparator is reversed from "L" to "H", therefore the output voltage becomes the GND level. The voltage level of Point A means a detector threshold voltage (-V_{DET}).
- Step 3. When the supply voltage is lower than the minimum operating voltage, the operation of the output transistor becomes indefinite. The output voltage is equal to the pull-up voltage.
- Step 4. The output voltage is equal to the GND level.
- Step 5. At Point "B", Vref ≤ V_{DD}×Rb/(Ra+Rb) is true, as a result, the output of comparator is reversed from "H" to "L", then the output voltage is equal to the pull-up voltage. The voltage level of Point B means a released voltage (+V_{DET}).
- *) The difference between a released voltage and a detector threshold voltage is a detector threshold hysteresis.

Operation of R3114xxx1C



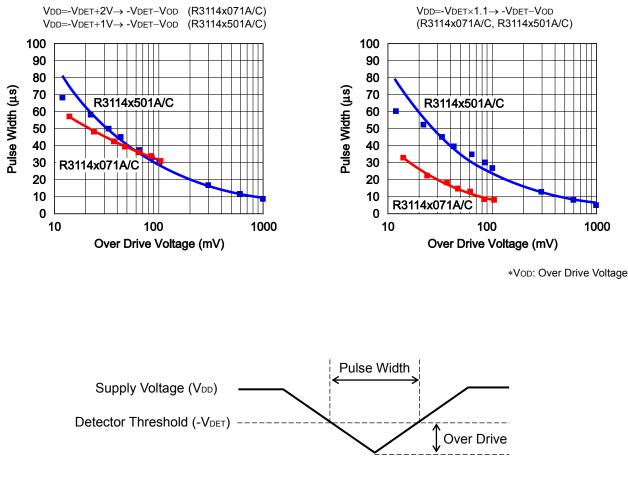
Operation Diagram

• Explanation of operation

- Step 1. The output voltage is equal to the supply voltage (V_{DD}).
- Step 2. At Point "A", Vref $\geq V_{DD} \times (Rb+Rc)/(Ra+Rb+Rc)$ is true, as a result, the output of comparator is reversed from "L" to "H", therefore the output voltage becomes the GND level. The voltage level of Point A means a detector threshold voltage (-V_{DET}).
- Step 3. When the supply voltage is lower than the minimum operating voltage, the operation of the output transistor becomes indefinite.
- Step 4. The output voltage is equal to the GND level.
- Step 5. At Point "B", Vref ≤ V_{DD×}Rb/(Ra+Rb) is true, as a result, the output of comparator is reversed from "H" to "L", then the output voltage is equal to the supply voltage (V_{DD}). The voltage level of Point B means a released voltage (+V_{DET}).
- *) The difference between a released voltage and a detector threshold voltage is a detector threshold hysteresis.

Detector Operation vs. glitch input voltage to the VDD pin

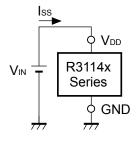
When the R3114x is at released, if the pulse voltage which the detector threshold or lower voltage, the graph below means that the relation between pulse width and the amplitude of the swing to keep the released state for the R3114x.



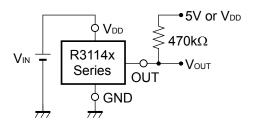
VDD Input Waveform

This graph shows the maximum pulse conditions to keep the released voltage. If the pulse with larger amplitude or wider width than the graph above, is input to V_{DD} pin, the reset signal may be output.

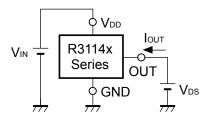
TEST CIRCUITS



Supply Current Test Circuit

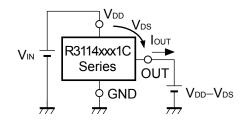


Detector Threshold Test Circuit (Pull-up circuit is not necessary for CMOS Output type.)

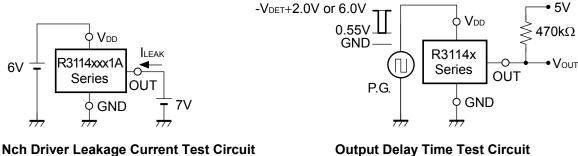


Nch Driver Output Current Test Circuit

*Apply to Nch Driver Output type only



Pch Driver Output Current Test Circuit *Apply to CMOS Output type only



Output Delay Time Test Circuit (Pull-up circuit is not necessary for CMOS Output type.)

R3114x151A/C

Topt=85°C

Topt=25°C

Topt=-40°C

1.0

0.8

0.6

0.4

0.2

0

1.0

0.8

0.6

0.4

0.2

0

0

1

2

3

4

Input Voltage VDD (V)

5

6

7

Supply Current Iss (µA)

0

1

2

Topt=85°C

. Topt=25°C

Topt=-40°C

3

Input Voltage VDD (V)

R3114x451A/C

4

5

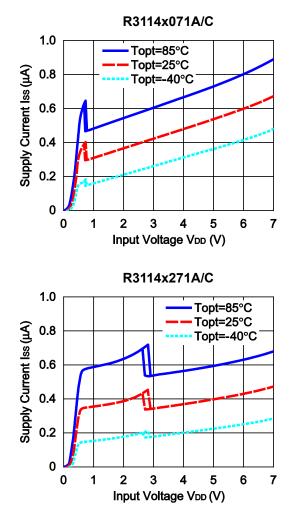
6

7

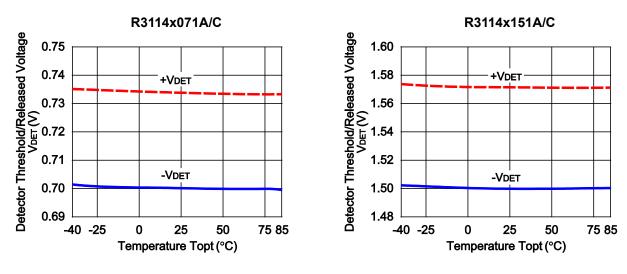
Supply Current Iss (µA)

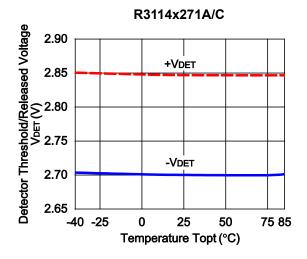
TYPICAL CHARACTERISTICS

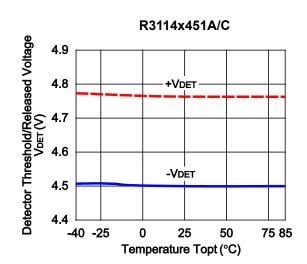
1) Supply Current vs. Input Voltage



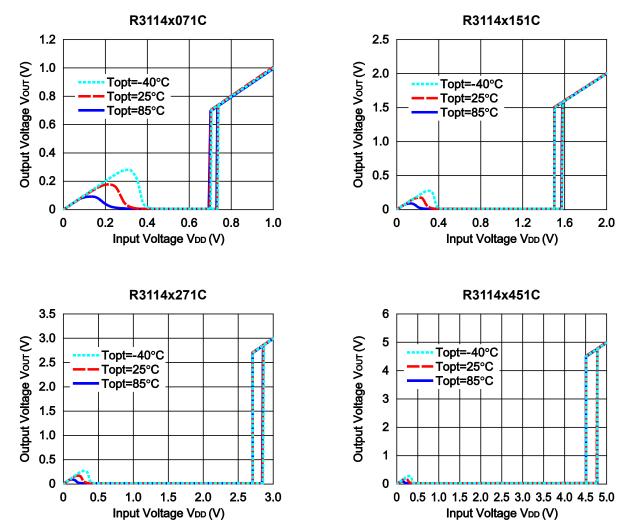
2) Detector Threshold vs. Temperature

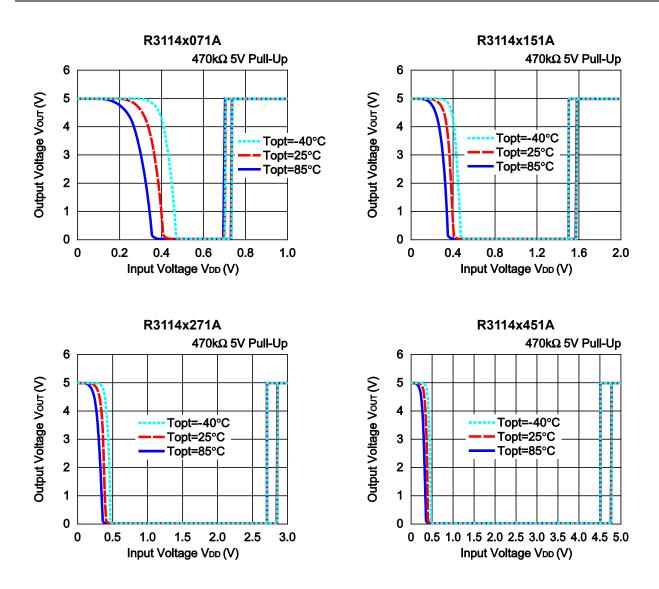




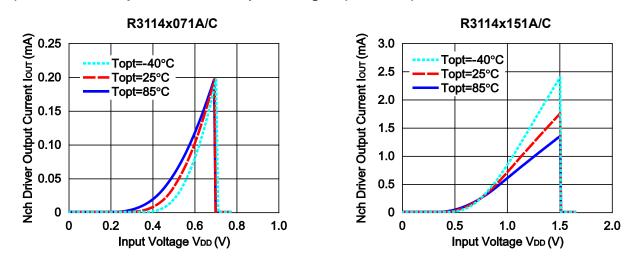


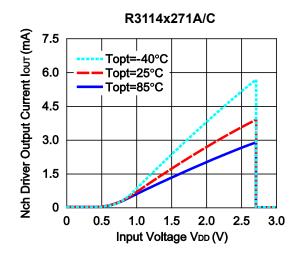
3) Output Voltage vs. Input Voltage

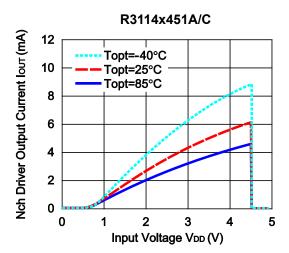




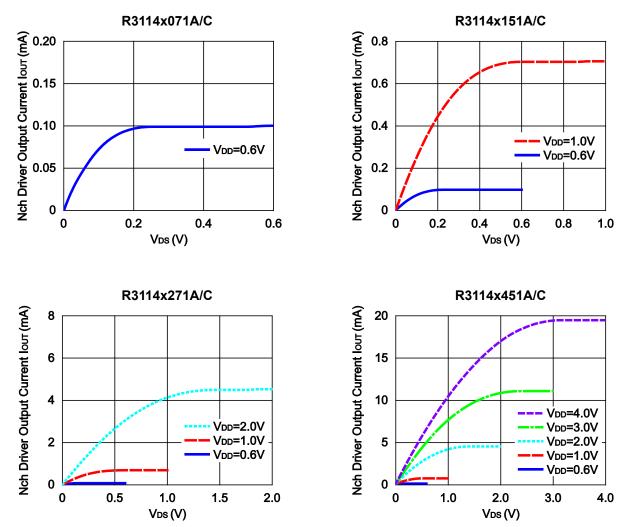
4) Nch Driver Output Current vs. Input Voltage (VDs=0.5V)

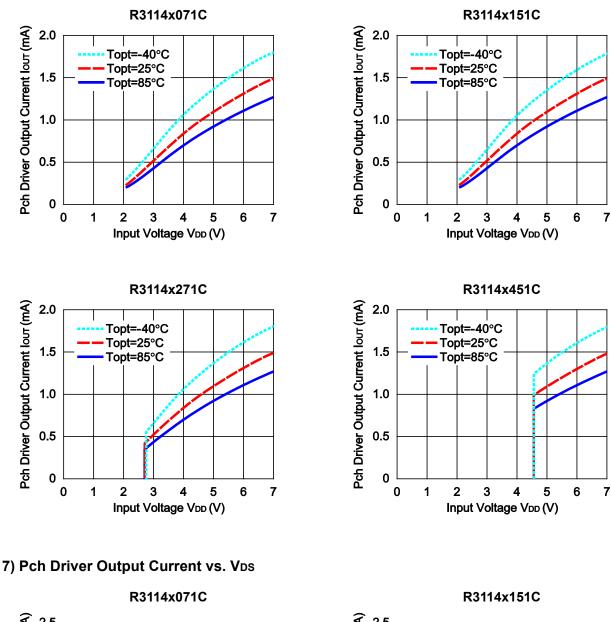




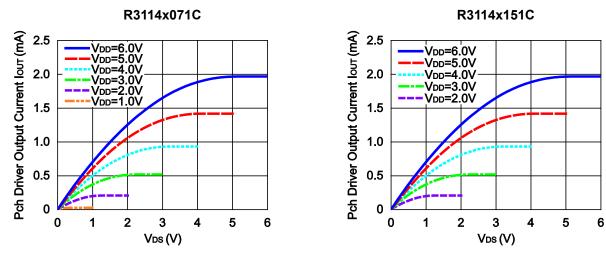


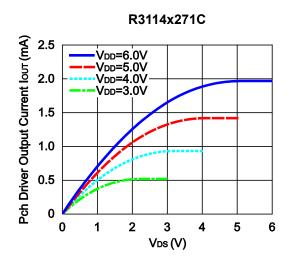
5) Nch Driver Output Current vs. VDs

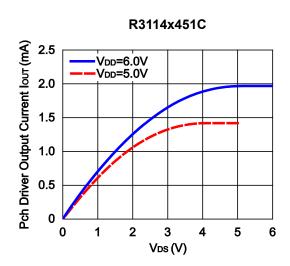




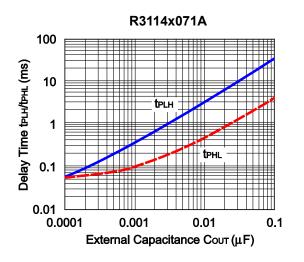
6) Pch Driver Output Current vs. Input Voltage (VDs=-2.1V)

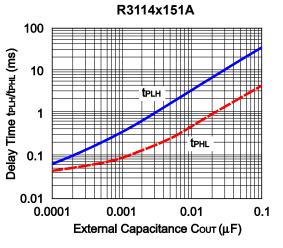


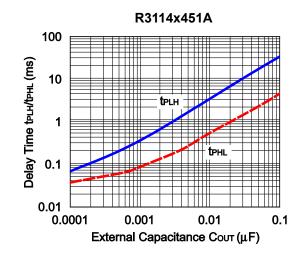




8) Output Delay Time vs. External Capacitance







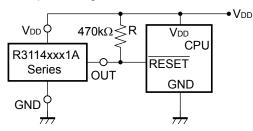
100 (su) Hqui 10 0.1 0.001 0.001 0.001 0.001 0.001 0.001 0.001 0.001 0.01 0.01 0.01 0.01 0.01 0.01 0.01 0.01 0.01 0.01 0.01

R3114x271A

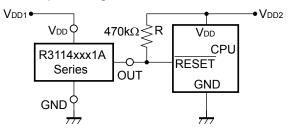
TYPICAL APPLICATION

• R3114xxx1A CPU Reset Circuit 1 (Nch Open Drain Output)

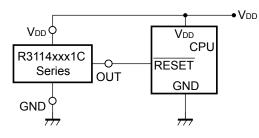
Case1. Input Voltage to R3114xxx1A is equal to Input Voltage to CPU



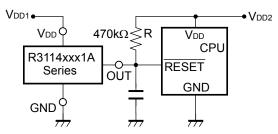
Case2. Input Voltage to R3114xxx1A is unequal to Input Voltage to CPU



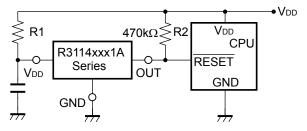
• R3114xxx1C CPU Reset Circuit (CMOS Output)



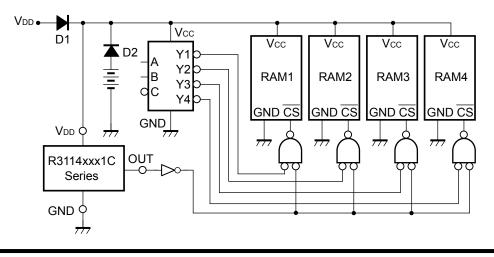
 R3114xxx1A Output Delay Time Circuit 1 (Nch Open Drain Output)

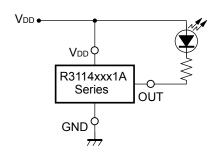


• R3114xxx1A Output Delay Time Circuit 2 (Nch Open Drain Output)



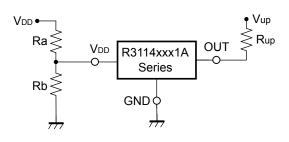
Memory Back-up Circuit



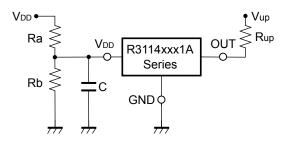


 Voltage level Indicator Circuit (lighted when the power runs out) (Nch Open Drain Output)

 Detector Threshold Adjustable Circuit 1 (Nch Open Drain Output)



• Detector Threshold Adjustable Circuit 2 (Nch Open Drain Output)



Adjustable Detector Threshold=(-VDET)×(Ra+Rb)/Rb

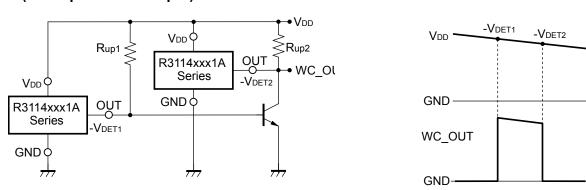
Hysteresis Voltage=(VHYS)×(Ra+Rb)/Rb

- *1) To prevent oscillation, set $Ra \le 1k\Omega$, $Rb \le 100\Omega$.
- *2) If the value of Ra is set excessively large, voltage drop may occur caused by the supply current of IC itself, and detector threshold and hysteresis voltage may vary.
- *3) If Vup and VDD are connected, the voltage dropdown caused by Rup, may cause difference in the hysteresis voltage.

Adjustable Detector Threshold=(-VDET)×(Ra+Rb)/Rb

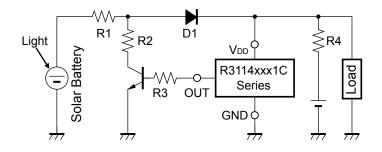
Hysteresis Voltage=(VHYS)×(Ra+Rb)/Rb

- *1) To prevent oscillation, set $Ra \le 100k\Omega$, $C \ge \le 0.01\mu F$.
- *2) If the value of Ra is set excessively large, voltage drop may occur caused by the supply current of IC itself, and detector threshold and hysteresis voltage may vary.
- *3) If Vup and VDD are connected, the voltage dropdown caused by Rup, may cause difference in the hysteresis voltage.
- *4) If the value of Ra, Rb and C are set excessively large, the delay of the start-up may become too long.



• Window Comparator Circuit (Nch Open Drain Output)

• Over-charge Preventing Circuit



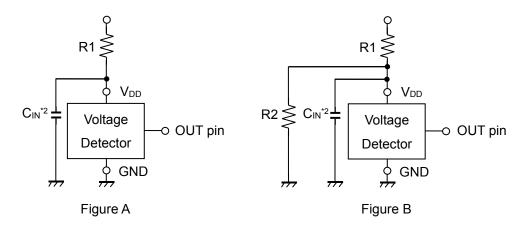
TECHNICAL NOTES

When connecting resistors to the device's input pin

When connecting a resistor (R1) to an input of this device, the input voltage decreases by [Device's Consumption Current] x [Resistance Value] only. And, the cross conduction current^{*1}, which occurs when changing from the detecting state to the release state, is decreased the input voltage by [Cross Conduction Current] x [Resistance Value] only. And then, this device will enter the re-detecting state if the input voltage reduction is larger than the difference between the detector voltage and the released voltage.

When the input resistance value is large and the VDD is gone up at mildly in the vicinity of the released voltage, repeating the above operation may result in the occurrence of output.

As shown in Figure A/B, set R1 to become 100 k Ω or less as a guide, and connect C_{IN} of 0.1 μ F and more to between the input pin and GND. Besides, make evaluations including temperature properties under the actual usage condition, with using the evaluation board like this way. As a result, make sure that the cross conduction current has no problem.



*1 In the CMOS output type, a charging current for OUT pin is included.

*² Note the bias dependence of capacitors.

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